Accretch Prober Audit Sheet	Sample
General:	
Serial Number	
MFG DATE	
Model	UF3000
Software Revision	NA
Internal ID#	NA
CE Mark	NA
Confirm Standard Configuration includes:	
Configured for 8" or 12" Wafers	12"
Chuck Type (Gold or Nickel)	Nickel (25~120'C)
Hard Disk Disk Size?	NA
3.5" 2HD/DD	NA
Magneto-Optical Drive (MO Drive)	N
Head Stage (details)	Y
Single Loader/Elevator	Dual Port
Loader Type - FOUP or Open Cassette	FOUP
Manual Wafer Inspection Transfer Unit	Inspection tray
Dual Robotic Wafer Transport Arms	Y
Pre-Alignment Stage Unit	Y
Auto Needle Alignment	Y
Advanced Wafer Alignment Unit	N
Alignment Camera	Y
Dual (X & Y) Heidenhain Scales	Y
Quad-Pod Z Stage	N
Color LCD Control Panel with Touch Panel Switches	Y
Alarm Lamp Pole	Y
Options:	
Visual Microscope	N
Second Loader/Elevator	N
Air Cooled Chuck	N
Chiller Type	N
Light Free Probing and Ultra Low Noise Probing	N
Wafer ID Recognition Option (type)	Y
Needle Cleaning Option (Wafer type, Driven Disc type, Stage, Brush, Wafer, etc list all.)	Wafer Type
Multi-Site Parallel Probing Option	Y
Fail Mark Inspection	Y
Probe Mark Inspection	Y
High Force (Tripod) Z Drive	N
Auto Cleaning Unit Profiler Option	N
GPIB Interface Option	Y
Ethernet Interface Option	Y
Mechnical Tester I/F, Tester Model	T5377
ACC (Automatic Probe card Changer)	Y
Image Processing Board	N
Bump Height Settings Option	N
Group Index Option	N
Multi-Pass Probe Option	N
TAG Reader for FOUP (OCR Function)	N
Twin Thermometer for Wafer Chuck Option	N
Remote Terminal Option	N
Printer (type)	N
Manipulator (type)	HF hinge
Network Option (Veganet, GEM/CMS, Light-Veganet)	GEM
Mini Environment	No
Manuals	No
Other Comments	
General Condition:	Running Production